

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32G071R8T3	755W*460XXXY	A	998Z	2023-11-09
	Amount	UoM	Unit type	ST ECOPACK Grade
	362.46	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), immersion	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	10x10	64	L bend	
Comment	Package : 5W LQFP 64 10x10x1.4 1 0051434			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	755W*460XXY				6000001.0	999998.1				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	5.085	mg	supplier	die	Silicon (Si)	7440-21-3		4.888	mg	961259	13486				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.009	mg	1770	25				
				supplier	metallization	Copper (Cu)	7440-50-8		0.084	mg	16519	232				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.027	mg	5310	74				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	197	3				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	197	3				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.021	mg	4130	58				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.054	mg	10619	149				
				Glue Epoxy (3230)	M-011 Other inorganic materials	0.692	mg	Supplier	Metals	Silver (Ag)	7440-22-4		0.564	mg	815000	1556
								Supplier	Plastics/polymers	2,2'-(Methylenebis(phenyleneoxymethylene))	39817-09-9		0.021	mg	30000	58
Supplier	Organic Compounds	Dihydro-3-(tetrapropenyl)furan-2,5-dione	26544-38-7						0.021	mg	30000	58				
Supplier	Organic Compounds	Epoxy resin	Proprietary						0.021	mg	30000	58				
Supplier	Organic Compounds	Dodecylloxirane	3234-28-4						0.021	mg	30000	58				
Supplier	Organic Compounds	Hexahydromethylphthalic anhydride	25550-51-0						0.021	mg	30000	58				
Supplier	Organic Compounds	Epoxy resin modifier	Proprietary						0.021	mg	30000	58				
Supplier	Metallic compounds	Copper oxide	1317-38-0						0.003	mg	5000	8				
Encapsulation (EME-G6315HQ)	M-011 Other inorganic materials	249.720	mg					Supplier	Plastics/polymers	Epoxy Resin A	Proprietary		5.244	mg	21000	14468
								Supplier	Plastics/polymers	Epoxy Resin B	Proprietary		5.244	mg	21000	14468
				Supplier	Plastics/polymers	Phenol Resin	Proprietary		13.984	mg	56000	38581				
				Supplier	Glass	Silica(Amorphous)A	60676-86-0		194.894	mg	780450	537698				
				Supplier	Glass	Silica(Amorphous)B	7631-86-9		28.798	mg	115320	79452				
				Supplier	Non-metals	Carbon Black	1333-86-4		1.556	mg	6230	4293				
Bonding Wire (Au)	Bonding Wire	1.225	mg	Supplier	Metals	Gold (Au)	7440-57-5		1.225	mg	1000000	3380				
External Plating (Sn)	M-011 Other inorganic materials	1.438	mg	Supplier	Metals	Tin (Sn)	7440-31-5		1.438	mg	1000000	3967				
Leadframe (C194 + Ag)	Copper & its alloys	104.300	mg	Supplier	Metals	Copper (Cu)	7440-50-8		101.400	mg	972200	279755				
				Supplier	Metals	Iron (Fe)	7439-89-6		2.388	mg	22900	6588				
				Supplier	Metals	Zinc (Zn)	7440-66-6		0.156	mg	1500	430				
				Supplier	Non-Metals	Phosphorus (P)	7723-14-0		0.031	mg	300	86				
				Supplier	Metals	Silver (Ag)	7440-22-4		0.323	mg	3100	891				